# 503062700 11/14/2014

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
TETSUNORI SOGA	10/21/2014

### **RECEIVING PARTY DATA**

Name:	THREE BOND FINE CHEMICAL CO., LTD.
Street Address:	1-1 OYAMA-CHO, MIDORI-KU, SAGAMIHARA-SHI
City:	KANAGAWA
State/Country:	JAPAN
Postal Code:	252-0146

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14401451

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	62284
NAME OF SUBMITTER:	GARRETT V. DAVIS
SIGNATURE:	/Garrett V. Davis/
DATE SIGNED:	11/14/2014

## **Total Attachments: 2**

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PATENT 503062700 REEL: 034178 FRAME: 0134

Attorney Docket No.: 62284

#### **ASSIGNMENT - U.S. Application**

W	HE	RE	AS.
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1. Tetsunori SOGA, c/o Three Bond Fine Chemical Co., Ltd., 1-1 Oyama-cho, Midori-ku, Sagamihara-shi, Kanagawa 252-0146 Japan, and a citizen of JP;

(herein called "THE UNDERSIGNE	D") has made an invention and has filed an application for Letters
Patent of the United States on	for this invention, which application is entitled
CURABLE RESIN COMPOSITION	AND PRIMER COMPOSITION and which has been given Serial
Number;	

AND WHEREAS, Three Bond Fine Chemical Co., Ltd. (herein called "ASSIGNEE"), a corporation organized under the laws of <u>JP</u>, and having an office and place of business at <u>1-1 Oyama-cho, Midori-ku</u>, <u>Sagamihara-shi, Kanagawa 252-0146 Japan</u>, wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of good and valuable consideration, the/receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sells, assigns and transfers to the ASSIGNEE, its successors and assigns, the entire right, title and interest for all countries in and to the invention disclosed in the aforesaid application, and in and to the said application, all divisionals, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said invention including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and THE UNDERSIGNED hereby authorizes and requests the Commissioner of Patents to issue any and all United States Letters Patent for the aforesaid invention to the ASSIGNEE of the entire right, title and interest in and to the same, for the use of the ASSIGNEE, its successors and assigns.

THE UNDERSIGNED hereby agrees that THE UNDERSIGNED, its executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to THE UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest in the ASSIGNEE, its successors or assigns the entire right, title and interest in and to the said invention, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represents and agrees with said ASSIGNEE its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by THE UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by THE UNDERSIGNED.

THE UNDERSIGNED hereby authorizes and requests the insertion in the following parenthetical (Application No. 14/401,451, filed Nov. 14, 2014) the application number and filing date of said application when such information is known if such information is not already provided herein.

Attorney De	ocket	No.:
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IN TESTIMONY WHEREOF, THE UNDERSIGNED has hereunto set its hand on the date indicated below.

Tetsunori SOGA

Printed Name Sign

Tetsunori SOGA

10,21,

Note: No legalization or other witness required

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PATENT REEL: 034178 FRAME: 0136

**RECORDED: 11/14/2014**